

# OL-NVT4857

wafer level chip-scale package; 20 bumps; 2.1 x 1.7 x 0.49 mm (Backside coating included)

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	WLCSP
<b>Package type industry code</b>	WLCSP20
<b>Package style descriptive code</b>	UC (uncased chip)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	21-7-2015

Table 1. Package summary

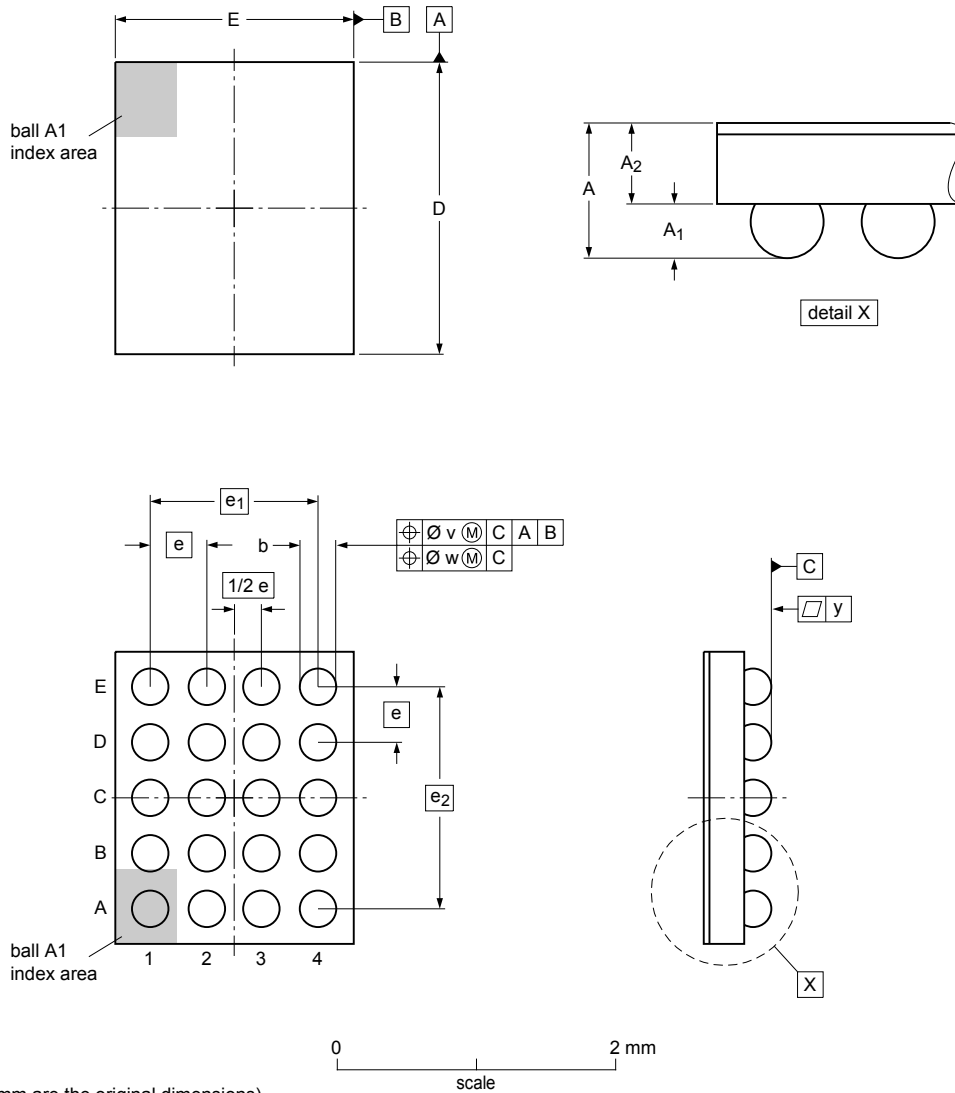
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.07	-	2.1	2.13	mm
E	package width	2.07	-	2.1	2.13	mm
A	seated height	0.45	-	0.49	0.53	mm
A <sub>2</sub>	package height	0.265	-	0.29	0.315	mm
e	nominal pitch	-	-	0.4	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	20	-	



wafer level chip-scale package; 20 bumps; 2.1 x 1.7 x 0.49 mm (Backside coating included)

## 2. Package outline

WLCSP20: wafer level chip-scale package; 20 bumps; 2.1 x 1.7 x 0.49 mm (Backside coating included) NVT4857



Dimensions (mm are the original dimensions)

Unit	A	A <sub>1</sub>	A <sub>2</sub>	b	D	E	e	e <sub>1</sub>	e <sub>2</sub>	v	w	y
max	0.53	0.23	0.315	0.29	2.13	1.73						
mm nom	0.49	0.20	0.290	0.26	2.10	1.70	0.4	1.2	1.6	0.15	0.05	0.05
min	0.45	0.17	0.265	0.23	2.07	1.67						

Note: Backside coating 40 μm

wlcs20\_nvt4857\_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
NVT4857					-15-06-03- 15-07-21

Fig. 1. Package outline WLCSP20 (OL-NVT4857)

wafer level chip-scale package; 20 bumps; 2.1 x  
1.7 x 0.49 mm (Backside coating included)

### 3. Legal information

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